PHILIPS 74ABT16823A Electronic component datasheet

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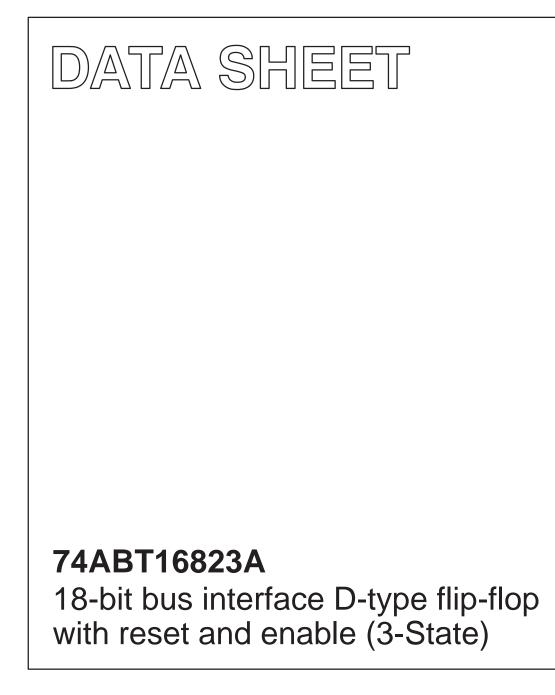
The 74ABT16823A 18-bit bus interface register is designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider data/address paths of buses carrying parity.

The 74ABT16823A has two 9-bit wide buffered registers with Clock Enable (nCE) and Master Reset (nMR) which are ideal for parity bus interfacing in high microprogrammed systems.

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INTEGRATED CIRCUITS



Product data Replaces data sheet 74ABT16823A/ABTH16823A of 1998 Feb 27 2004 Feb 02

Philips Semiconductors





74ABT16823A

FEATURES

- Two sets of high speed parallel registers with positive edge-triggered D-type flip-flops
- Ideal where high speed, light loading, or increased fan-in are required with MOS microprocessors
- Live insertion/extraction permitted
- Power-up 3-State
- Power-up Reset
- Output capability: +64 mA/-32 mA
- Latch-up protection exceeds 500 mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT16823A 18-bit bus interface register is designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider data/address paths of buses carrying parity.

The 74ABT16823A has two 9-bit wide buffered registers with Clock Enable (n \overline{CE}) and Master Reset (n \overline{MR}) which are ideal for parity bus interfacing in high microprogrammed systems.

The registers are fully edge-triggered. The state of each D input, one set-up time before the LOW-to-HIGH clock transition is transferred to the corresponding flip-flop's Q output.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25 °C; GND = 0 V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nCP to nQx	C _L = 50 pF; V _{CC} = 5 V	2.3 1.9	ns
C _{IN}	Input capacitance	$V_I = 0 V \text{ or } V_{CC}$	4	pF
C _{OUT}	Output capacitance	$V_O = 0 V \text{ or } V_{CC}$; 3-State	6	pF
Iccz	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5 V$	500	μΑ
I _{CCL}	Quiocount supply current	Outputs low; V_{CC} = 5.5 V	9	mA

ORDERING INFORMATION

 $T_{amb} = -40 \circ C$ to $+85 \circ C$

Type number	Package	^v ackage			
	Name	Description	Version		
74ABT16823ADL	SSOP56	plastic shrink small outline package; 56 leads; body width 7.5 mm	SOT371-1		
74ABT16823ADGG	TSSOP56	plastic thin shrink small outline package; 56 leads; body width 6.1 mm	SOT364-1		

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
2, 27	10E, 20E	Output enable input (active-LOW)
54, 52, 51, 49, 48, 47, 45, 44, 43 42, 41, 40, 38, 37, 36, 34, 33, 31	1D0-1D8 2D0-2D8	Data inputs
3, 5, 6, 8, 9, 10, 12, 13, 14 15, 16, 17, 19, 20, 21, 23, 24, 26	1Q0-1Q8 2Q0-2Q8	Data outputs
56, 29	1CP, 2CP	Clock pulse input (active rising edge)
55, 30	1CE, 2CE	Clock enable input (active-LOW)
1, 28	1 <u>MR</u> , 2 <u>MR</u>	Master reset input (active-LOW)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0 V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

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PIN CONFIGURATION

		$\neg \neg$	ľ	
1MR	1	-	56	1CP
10E	2		55	1CE
1Q0	3		54	1D0
GND	4		53	GND
1Q1	5		52	1D1
1Q2	6		51	1D2
V _{CC}	7		50	V _{CC}
1Q3	8		49	1D3
1Q4	9		48	1D4
1Q5	10		47	1D5
GND	11		46	GND
1Q6	12		45	1D6
1Q7	13		44	1D7
1Q8	14		43	1D8
2Q0	15		42	2D0
2Q1	16		41	2D1
2Q2	17		40	2D2
GND	18		39	GND
2Q3	19		38	2D3
2Q4	20		37	2D4
2Q5	21		36	2D5
V _{CC}	22		35	V _{CC}
2Q6	23		34	2D6
2Q7	24		33	2D7
GND	25		32	GND
2Q8	26		31	2D8
20E	27		30	2CE
2MR	28		29	2CP
		SHOO	014	
		3800	1014	

LOGIC SYMBOL (IEEE/IEC)

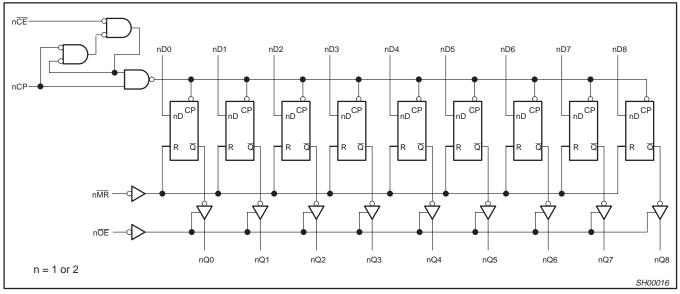
				1	
1 0E	2	EN1			
1MR	1	R2			
1CE	55 📐	G3			
1CP	56	> 3C4			
20E	27	EN5			
2MR	28	R6			
2CE	30	G7			
2CP	29	> 7C8			
100	54	4D	1.27	3	100
1D0 1D1	52	- 4D	1, 2 ∇	5	1Q0 1Q1
1D1 1D2	51			6	1Q1 1Q2
1D2 1D3	49			8	1Q2 1Q3
1D3 1D4	48			9	1Q3 1Q4
1D4 1D5	47			10	1Q4 1Q5
1D5 1D6	45			12	1Q5
1D0 1D7	44	I		13	1Q7
1D7 1D8	43			14	1Q7
2D0	42		5.05	15	2Q0
2D0 2D1	41	- 8D	5,6∇	16	2Q0 2Q1
2D1 2D2	40			17	2Q1 2Q2
2D2 2D3	38			19	2Q2 2Q3
2D3 2D4	37			20	2Q3 2Q4
2D4 2D5	36	·		21	2Q4 2Q5
2D5 2D6	34			23	2Q5 2Q6
2D6 2D7	33	<u> </u>		24	2Q6 2Q7
2D7 2D8	31			25	2Q8
200					
				SH	100015

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Product data

LOGIC DIAGRAM



FUNCTION TABLE

		INPUTS			OUTPUTS	OPERATING MODE
nOE	nMR	nCE	nCP	nDx	nQ0 – nQ8	OFERATING MODE
L	L	Х	Х	Х	L	Clear
L	Н	L	Ŷ	h	Н	Load and read data
L	Н	L	Ŷ	I	L	
L	Н	Н	\$	Х	NC	Hold
Н	Х	Х	Х	Х	Z	High impedance

High voltage level H =

h = High voltage level one set-up time prior to the LOW-to-HIGH clock transition

L = Low voltage level I

Low voltage level one set-up time prior to the LOW-to-HIGH clock transition =

NC= No change

= Don't care X Z ↑↑

High impedance "off" state =

LOW-to-HIGH clock transition =

= Not a LOW-to-HIGH clock transition

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT	
V _{CC}	DC supply voltage		-0.5 to +7.0	V	
I _{IK}	DC input diode current	V _I < 0 V	-18	mA	
VI	DC input voltage ³		-1.2 to +7.0	V	
Ι _{ΟΚ}	DC output diode current	V _O < 0 V	-50	mA	
V _{OUT}	DC output voltage ³	output in Off or HIGH state	-0.5 to +5.5	V	
1		output in LOW state	128		
IOUT	DC output current	output in HIGH state	-64	- mA	
T _{stg}	Storage temperature range		-65 to 150	°C	

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
 The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM		
SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
VIH	HIGH-level input voltage	2.0	-	V
V _{IL}	LOW-level input voltage	-	0.8	V
I _{OH}	HIGH-level output current	-	-32	mA
I _{OL}	LOW-level output current	-	64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

		TEST CONDITIONS			LIMIT	s		
SYMBOL	PARAMETER			T _{amb} = +25 °C			-40 °C to 5 °C	UNIT
			MIN	ТҮР	MAX	MIN	MAX	
V _{IK}	Input clamp voltage	$V_{CC} = 4.5 \text{ V}; \text{ I}_{IK} = -18 \text{ mA}$	-	-0.9	-1.2	-	-1.2	V
		V_{CC} = 4.5 V; I_{OH} = –3 mA; V_{I} = V_{IL} or V_{IH}	2.5	2.9	-	2.5	-	V
V _{OH}	HIGH-level output voltage	V_{CC} = 5.0 V; I_{OH} = –3 mA; V_{I} = V_{IL} or V_{IH}	3.0	3.4	-	3.0	-	V
		V_{CC} = 4.5 V; I_{OH} = –32 mA; V_{I} = V_{IL} or V_{IH}	2.0	2.4	-	2.0	-	V
V _{OL}	LOW-level output voltage	V_{CC} = 4.5 V; I_{OL} = 64 mA; V_{I} = V_{IL} or V_{IH}	-	0.42	0.55	-	0.55	V
V _{RST}	Power-up output LOW voltage ³	V_{CC} = 5.5 V; I_{OL} = 1 mA; V_{I} = GND or V_{CC}	-	0.13	0.55	-	0.55	V
l _l	Input leakage curent	V_{CC} = 5.5 V; V_{I} = V_{CC} or GND	-	±0.01	±1	-	±1	μA
I _{OFF}	Power-off leakage current	V_{CC} = 0.0 V; V_O or $V_I \leq~4.5$ V	-	±5.0	±100	-	±100	μA
I _{PU/PD}	Power-up/down 3-State output current ⁴	$V_{CC} = 2.1 \text{ V}; V_O = 0.5 \text{ V}; V_I = \text{GND or } V_{CC};$ $V_{OE} = \text{Don't care}$	-	±5.0	±50	-	±50	μA
I _{OZH}	3-State output HIGH current	V_{CC} = 5.5 V; V_{O} = 2.7 V; V_{I} = V_{IL} or V_{IH}	-	1.0	10	-	10	μΑ
I _{OZL}	3-State output LOW current	V_{CC} = 5.5 V; V_{O} = 0.5 V; V_{I} = V_{IL} or V_{IH}	-	-1.0	-10	-	-10	μΑ
ICEX	Output HIGH leakage current	V_{CC} = 5.5 V; V_{O} = 5.5 V; V_{I} = GND or V_{CC}	-	50	50	-	50	μΑ
Ι _Ο	Output current ¹	$V_{CC} = 5.5 \text{ V}; V_{O} = 2.5 \text{ V}$	-50	-80	-180	-50	-180	mA
I _{ССН}		V_{CC} = 5.5 V; Outputs HIGH; V _I = GND or V _{CC}	-	0.5	1	-	1	mA
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs LOW; V _I = GND or V _{CC}	-	9.0	19	-	19	mA
I _{CCZ}		$V_{CC} = 5.5V$; Outputs 3–State; $V_I = GND \text{ or } V_{CC}$	-	0.5	1	-	1	mA
ΔI _{CC}	Additional supply current per input pin ²	V_{CC} = 5.5V; one input at 3.4 V, other inputs at V_{CC} or GND	-	0.2	1	-	1	mA

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

2. This is the increase in supply current for each input at 3.4V.

3. For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.

4. This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. From V_{CC} = 2.1V to V_{CC} = 5V \pm 10% a transition time of up to 100µsec is permitted.

GND = 0 V, t_R = t_F = 2.5 ns, C_L = 50 pF, R_L = 500 Ω

AC CHARACTERISTICS

					LIM	ITS		
SYMBOL	PARAMETER	WAVEFORM	T _{amb} = +25 °C V _{CC} = + 5.0 V			T _{amb} = -40 ° V _{CC} = +5.0	UNIT	
			MIN	TYP	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	1	140	190	-	140		MHz
t _{PLH} t _{PHL}	Propagation delay nCP to nQx	1	1.4 1.2	2.3 1.9	3.2 2.6	1.4 1.2	3.7 2.9	ns
t _{PHL}	Propagation delay nMR to nQx	2	2.0	3.3	4.3	2.0	5.0	ns
t _{PZH} t _{PZL}	Output enable time to HIGH and LOW level	4 5	1.3 1.2	2.4 2.1	3.2 2.9	1.3 1.2	3.9 3.4	ns
t _{PHZ} t _{PLZ}	Output disable time from HIGH and LOW level	4 5	1.7 1.6	2.9 2.3	4.0 3.2	1.7 1.6	4.7 3.4	ns

AC SET-UP REQUIREMENTS

GND = 0 V, $t_R = t_F$ = 2.5 ns, C_L = 50 pF, R_L = 500 Ω

				LIM	ITS	
SYMBOL	PARAMETER	WAVEFORM	T _{amb} = V _{CC} =	+25 °C + 5.0 V	T _{amb} = −40 °C to +85 °C V _{CC} = +5.0 V ± 0.5V	UNIT
			MIN	TYP	MIN	1
t _s (H) t _s (L)	Set-up time, HIGH or LOW nDx to nCP	3	2.0 1.5	1.3 0.9	2.0 1.5	ns
t _h (H) t _h (L)	Hold time, HIGH or LOW nDx to nCP	3	1.5 1.5	-0.9 -1.2	1.5 1.5	ns
t _w (H) t _w (L)	nCP pulse width HIGH or LOW	1	3.3 3.3	1.7 1.7	3.3 3.3	ns
t _s (H) t _s (L)	Set-up time, HIGH or LOW $n\overline{CE}$ to nCP	3	1.5 2.0	0.9 0.9	1.5 2.0	ns
t _h (H) t _h (L)	Hold time, HIGH or LOW nCE to nCP	3	1.5 1.5	-0.8 -0.9	1.5 1.5	ns
t _w (L)	nMR pulse width, LOW	2	3.0	1.7	3.0	ns
t _{rec}	Recovery time nMR to nCP	2	2.5	1.0	2.5	ns

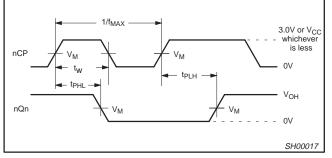
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Product data

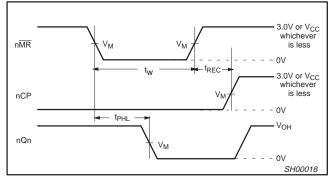
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AC WAVEFORMS

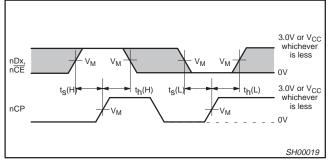
For all waveforms, $V_M = 1.5$ V. The shaded areas indicate when the input is permitted to change for predictable output performance.



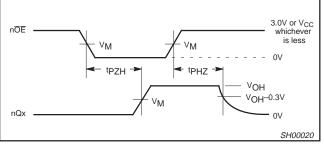
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



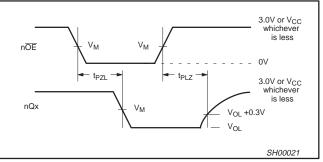
Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock Recovery Time



Waveform 3. Data Set-up and Hold Times



Waveform 4. 3-State Output Enable Time to HIGH Level and Output Disable Time from HIGH Level

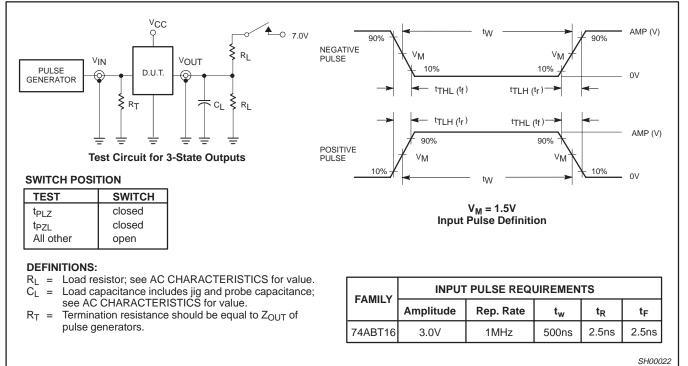


Waveform 5. 3-State Output Enable Time to LOW Level and Output Disable Time from LOW Level

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Product data

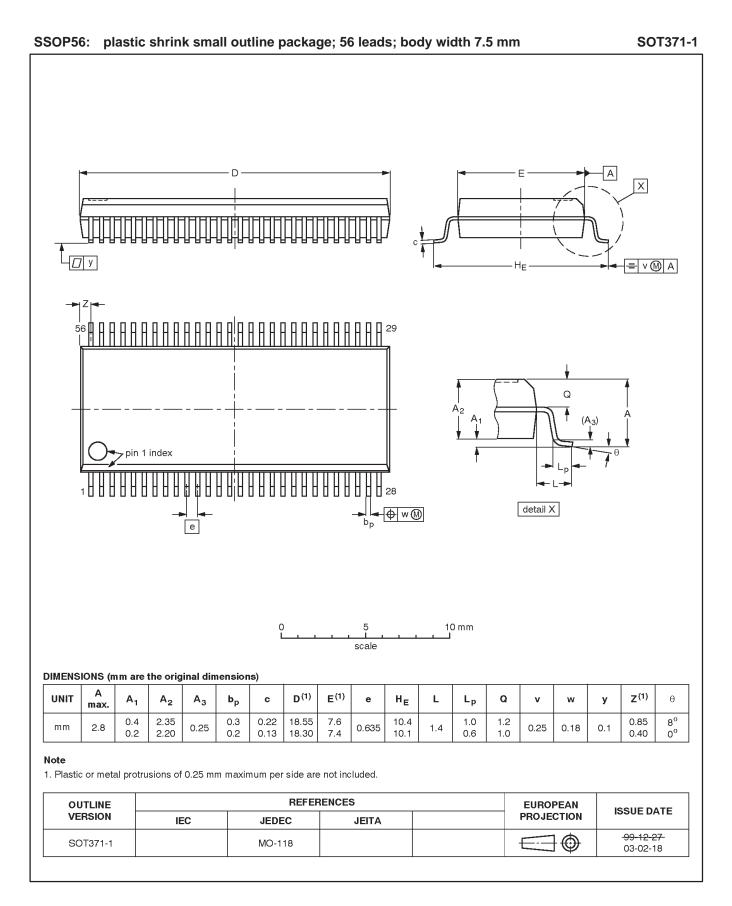
TEST CIRCUIT AND WAVEFORM



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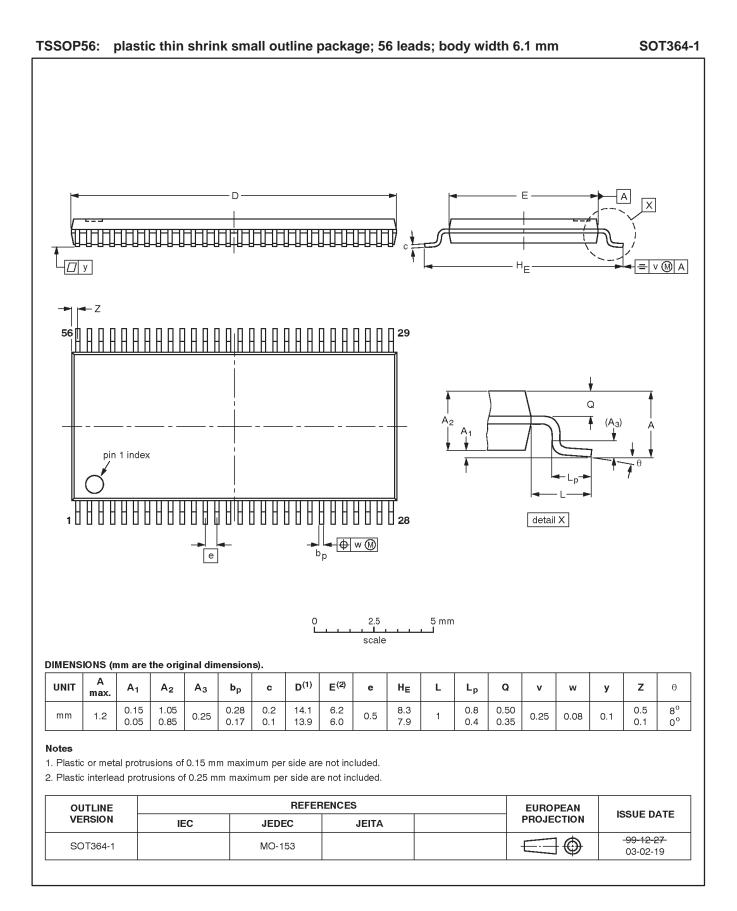
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Product data



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REVISION HISTORY

Rev	Date	Description
_3	20040202	Product data (9397 750 12833); 853-1791 ECN 01-A15432 of 27 January 2004. Replaces data sheet 74ABT_H16823A_2 of 1998 February 27 (9397 750 03502).
		Modifications:
		 Delete all references to 74ABTH16823A (product discontinued).
_2	19980227	Product specification (9397 750 03502); ECN 853-1791 19025 of 27 February 1998. Supersedes data of 1995 Sep 28.

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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